

PCN# 20140826000
Qualification of RFAB and TI Clark as Additional Fab Site
and Assembly/Test Site Options for Select DRV2603 Devices
Change Notification / Sample Request

Date: 9/2/2014

To: MOUSER PCN

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20140826000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DRV2603RUNR	null
DRV2603RUNT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20140826000		PCN Date:	09/02/2014	
Title:	Qualification of RFAB and TI Clark as Additional Fab Site and Assembly/Test Site Options for select DRV2603 devices				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept: Quality Services	
*Proposed 1st Ship Date:	12/02/2014	Estimated Sample Availability:	Date Provided at Sample request		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
PCN Details					
Description of Change:					
<p>This change notification is to announce the addition of RFAB and TI Clark as additional Fab site and Assembly/Test site options for select DRV2603 devices. The affected devices are listed in the Product Affected Section.</p>					
Fab Site:					
Current Site/Process/Wafer Diameter		Additional Site/Process/Wafer Diameter			
UMC-F8E/LBC8 Process/200mm		RFAB/LBC8 Process/300mm			
Assembly Site: There are no material set differences between MLA and TI-Clark. Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.					
Reason for Change:					
Continuity of supply.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					

Changes to product identification resulting from this PCN:

Fab Site

Current Chip Site	Chip Site Code (20L)	Chip Country Code (21 L)
UMC-F8E	CSO: U8E	JPN
New Chip Site	Chip Site Code (20L)	Chip Country Code (21 L)
RFAB	CSO: RFB	USA

Assembly Site

Current Assembly Site		
MLA	Assembly Site Origin (22L)	ASO: MYS
Clark-AT	Assembly Site Origin (22L)	ASO: QAB

Sample Product Shipping Label (not actual product label)

 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q: MSL '2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750			(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS
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ASSEMBLY SITE CODES: TI CLARK =I

Product Affected Devices

DRV2603CRUNR	DRV2603RUNR	DRV2603RUNT	DRV2603V1RUNR
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Qualification Report

New LBC8LV fab components in RFAB

Approved 09/17/2013

Attributes	Qual Device: DRV2603RUN	QBS Process: SH8350BCA0PAPG4_TIPI
Assembly Site	CLARK-AT	PHI
Package Family	QFN	TQFP
Flammability Rating	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	RFAB
Wafer Fab Process	LBC8LV	LBC8LV

- QBS: Qual By Similarity
- Qual Device DRV2603RUN is qualified at LEVEL2-260C

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DRV2603RUN	QBS Process: SH8350BCA0PAPG4_TIP1
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0
AC	Autoclave 121C	96 Hours	-	3/231/0
TC	Temperature Cycle - 65/150C	500 Cycles	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0
HTOL	Life Test, 125C	1000 Hours	-	3/224/0
HTOL	Life Test, 140C	480 Hours	3/231/0	-
HBM	ESD - HBM	1000 V	3/9/0	3/15/0
CDM	ESD - CDM	250 V	3/9/0	3/15/0
LU	Latch-up	(per JESD78)	3/18/0	3/24/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report

B-Stage Epoxy Ablestik 8006NS Enterprise Qual for QFN/SON package in Clark for DRV2603RUNR

Attributes	Qual Device: DRV2603RUNR	Qual Device: TPS71745DSER
Assembly Site	CLARK AT	CLARK AT
Package Family	WQFN	WSON
Flammability Rating	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	MIHO 8
Wafer Fab Process	LBC8LV	LBC7

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: DRV2603RUNR	Qual Device: TPS71745DSER
HAST	Biased HAST, 130C/85%RH	96 Hours	-	2/153/0
AC	Autoclave 121C	96 Hours	3/231/0	-
TC	Temperature Cycle, -65/+150C	500 Cycles	3/231/0	-
HTSL	High Temp Storage Bake, 150C	1000 Hours	3/231/0	-
MQ	Manufacturability	(per mfg. Site specification)	Pass	-
MSL	Thermal Path Integrity	Level 2 @ 260C	1/12/0	-
MSL	Moisture Sensitivity Level	Level 1 @ 260C	-	-
VM	Visual Quality Reliability Inspection	Pre-Stress	3/6/0	-
VM	Visual Quality Reliability Inspection	Post Temp Cycle	3/6/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com